

FEE TRANSMITTAL

Electronic Version v08

Stylesheet Version v08.0

**Title of
Invention**Solder Film Manufacturing Method, Heat Sink Furnished with Solder Film, and
Semiconductor-Device-and-Heat-Sink Junction

Application Number :

Date :

First Named Applicant: Mr. Katsuhiko Itakura

Attorney Docket Number: 39.036

TOTAL FEE AUTHORIZED \$ 1212

Patent fees are subject to annual revisions on or about October 1st of each year.

Filing as large entity

BASIC FILING FEE

| Fee Description | Fee Code | Amount \$ | Fee Paid \$ |
|--|----------|-----------|-------------|
| Utility Filing Fee | 1001 | 770 | 770 |
| Subtotal For Basic Filing Fees: \$ 770 | | | |

EXTRA CLAIM FEES

| Fee Description | Extra Claim | Fee Code | Amount \$ | Fee Paid \$ |
|--|-------------|----------|-----------|-------------|
| Total Claims : 28 | 8 | 1202 | 18 | 144 |
| Independent Claims : 6 | 3 | 1201 | 86 | 258 |
| Subtotal For Extra Claims Fees: \$ 402 | | | | |

ASSIGNMENT FEES

| Fee Description | Property Number | Quantity | Fee Code | Amount \$ | Fee Paid \$ |
|--|-----------------|----------|----------|-----------|-------------|
| Recording Each Patent Assignment Per Property Fee | 00000000 | 1 | 8021 | 40 | 40 |
| Subtotal For Additional Fees: \$40 | | | | | |

AUTHORIZED BILLING INFORMATION**The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:**

Credit account number: 3014
Expiration Date (YYYYMMDD): 2009-04-30
Authorized name: JAMES W JUDGE
Billing address: 99999